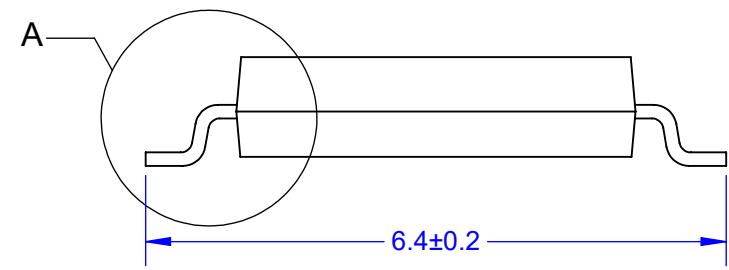
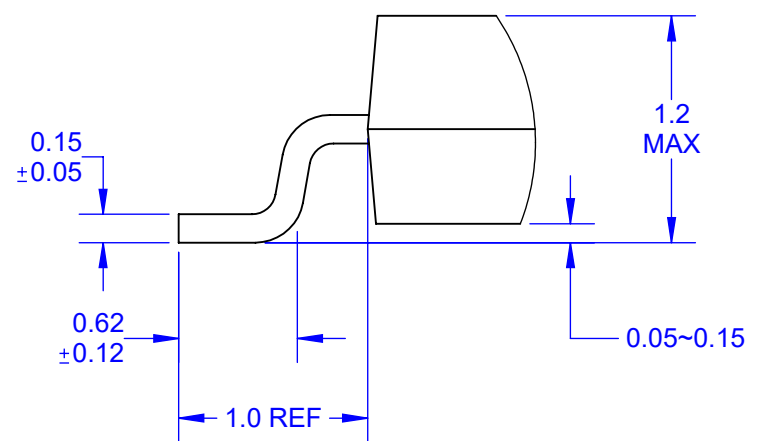


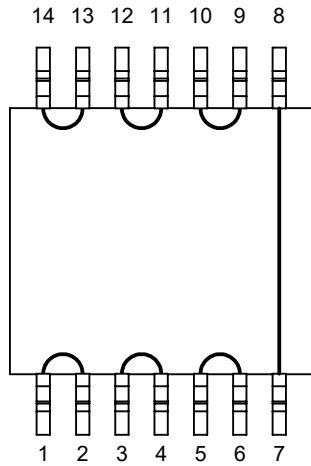
**DETAIL A
SCALE 25 : 1**



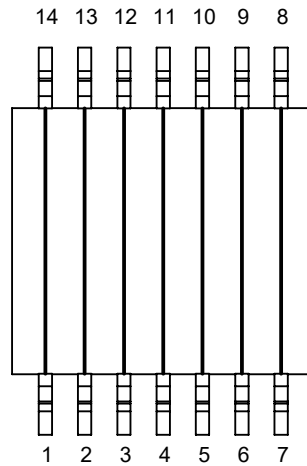
- Notes: (Unless Otherwise Specified)
- 1) DIMENSION IN mm.
 - 2) SEE JUMPER DIAGRAMS (PAGE 2).
 - 3) SEE PART NUMBER CONFIGURATION (PAGE 4).
 - 4) RECOMMENDED PC BOARD LAYOUT PATTERN (PAGE 6).

APPROVALS	DATE	TopLine®			
DRAWN T. Au	1/1/2022				
ENG M. Hart	1/1/2022	TITLE TSSOP14 JUMPER OUTLINE PACKAGE			
MFG		SCALE 8:1	SIZE A	DRAWING NO. 131414	REV A
QA					
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 7
REVISED					

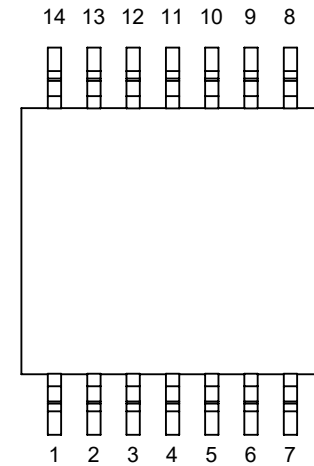
INTERNAL WIRING CIRCUIT (JUMPER) DAISY CHAIN PART NUMBER SUFFIX TOP VIEW



DE
DAISY CHAIN EVEN

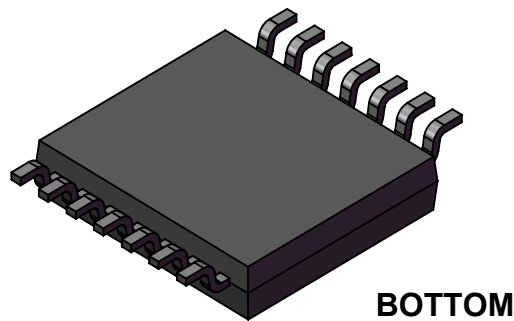
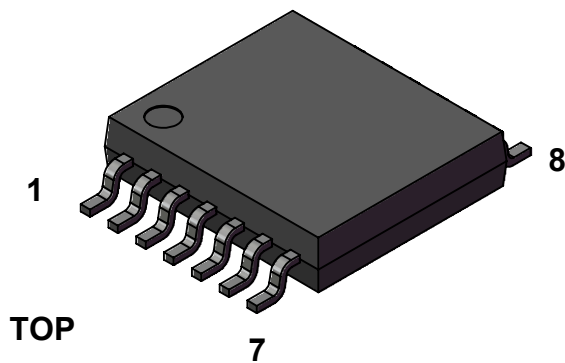


DC1414
JUMPER

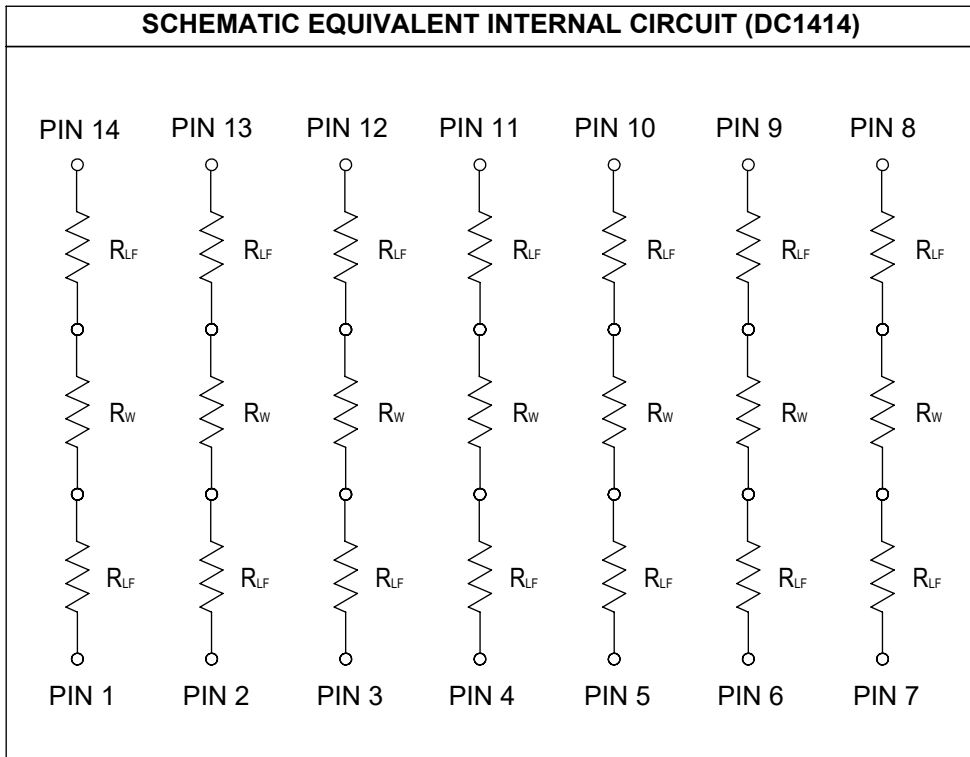


ISO
ISOLATED CIRCUIT
NO INTERNAL
CONNECTIONS

MODEL



TopLine®			
TITLE TSSOP14 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
8:1	A	131414	A
DO NOT SCALE DRAWING			SHEET 2 OF 7



R_W = GOLD WIRE-BOND.

R_{LF} = LEAD FRAME.

ELECTRICAL RESISTANCE MILLIOHM (DC) MAX	
CIRCUIT	PIN TO PIN
1 ~ 14	50 mΩ
2 ~ 13	50 mΩ
3 ~ 12	50 mΩ
4 ~ 11	50 mΩ
5 ~ 10	50 mΩ
6 ~ 9	50 mΩ
7 ~ 8	50 mΩ

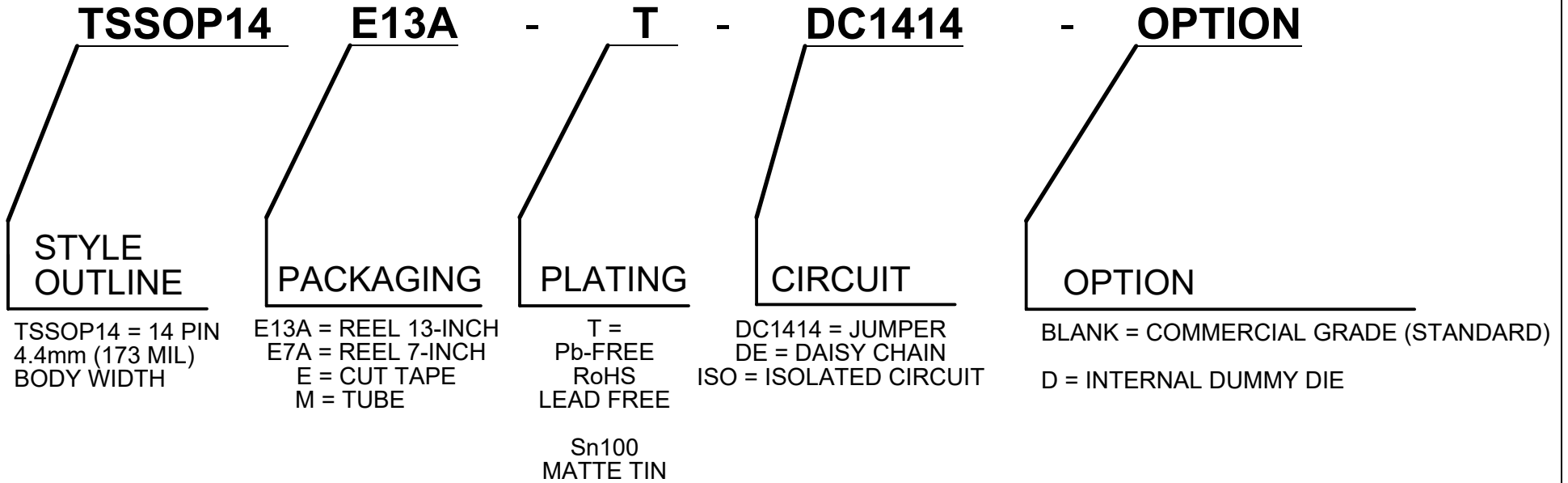
TEMPERATURE RATING	
JUNCTION TEMP T_J	150°C
STORAGE TEMP T_{stg}	-65°C TO 150°C
OPERATING TEMP	-65°C TO 150°C
PEAK REFLOW TEMP T_{reflow} 10 SECONDS	260°C

MAXIMUM ELECTRICAL (DC) RATING PER PIN	
WORKING VOLTAGE	100 V
CURRENT RATING	100mA
POWER @ 25°C	350 mW

THERMAL RESISTANCE	
JUNCTION TO AMBIENT ($T_a=25^\circ$) $R_{th(j-a)}$	350K/W

TopLine®			
TITLE		TSSOP14 JUMPER OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131414	A
DO NOT SCALE DRAWING			SHEET 3 OF 7

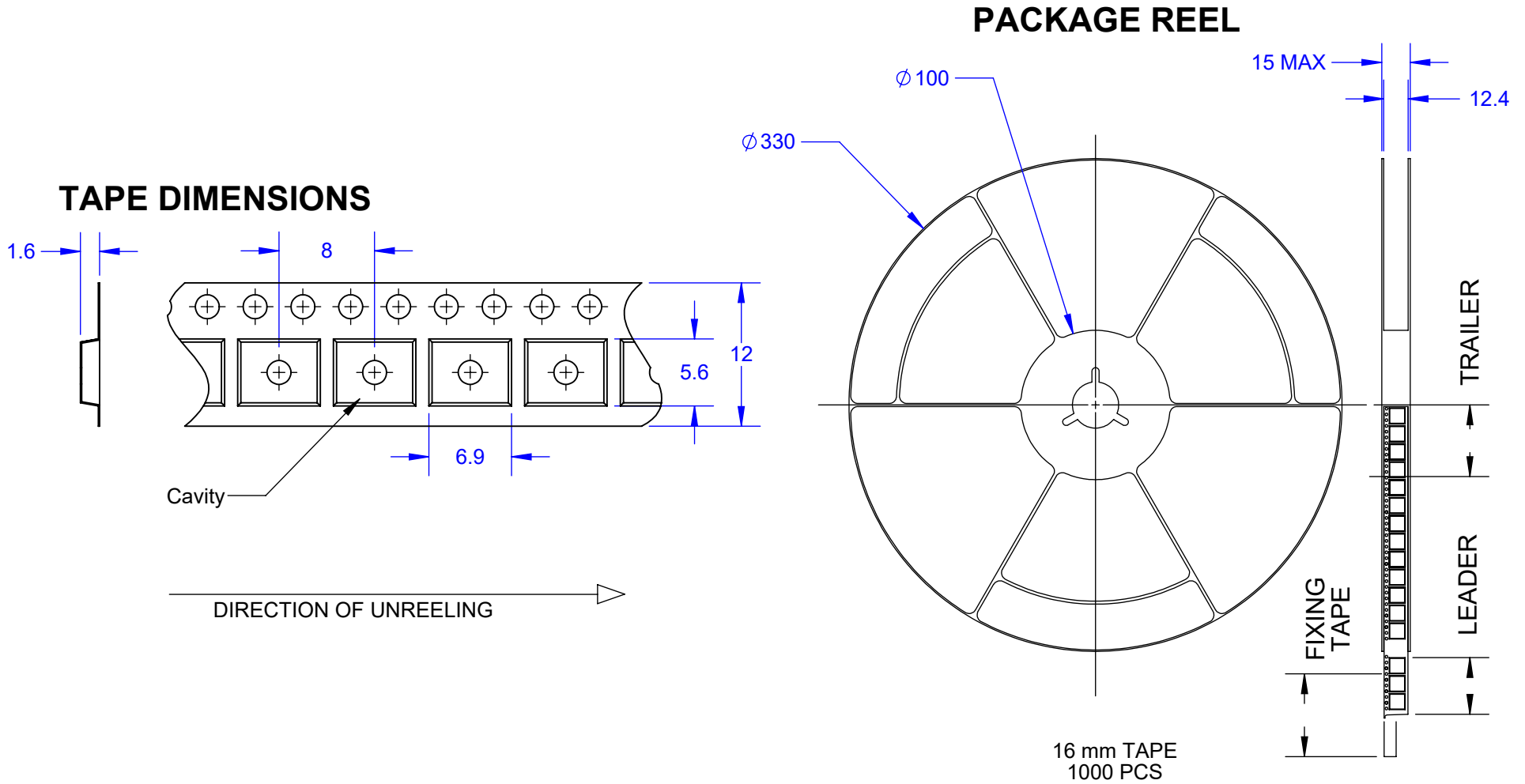
PART NUMBERING SYSTEM



PART NUMBER	SHORTED PINS	NOTES	RoHS Pb-FREE	MSL LEVEL
TSSOP14E13A-T-DC1414	1~14, 2~13, 3~12, 4~11, 5~10, 6~9, 7~8	7-WIRES	YES	1
TSSOP14E13A-T-DE	1~2, 3~4, 5~6, 7~8, 9~10, 11~12, 13~14	7-WIRES	YES	1
TSSOP14E13A-T	N/A	DUMMY	YES	1
TSSOP14E13A-T-ISO	NONE	FULLY ISOLATED	YES	1

TopLine®			
TITLE TSSOP14 JUMPER OUTLINE PACKAGE			
SCALE NONE	SIZE A	DRAWING NO. 131414	REV A
DO NOT SCALE DRAWING			SHEET 4 OF 7

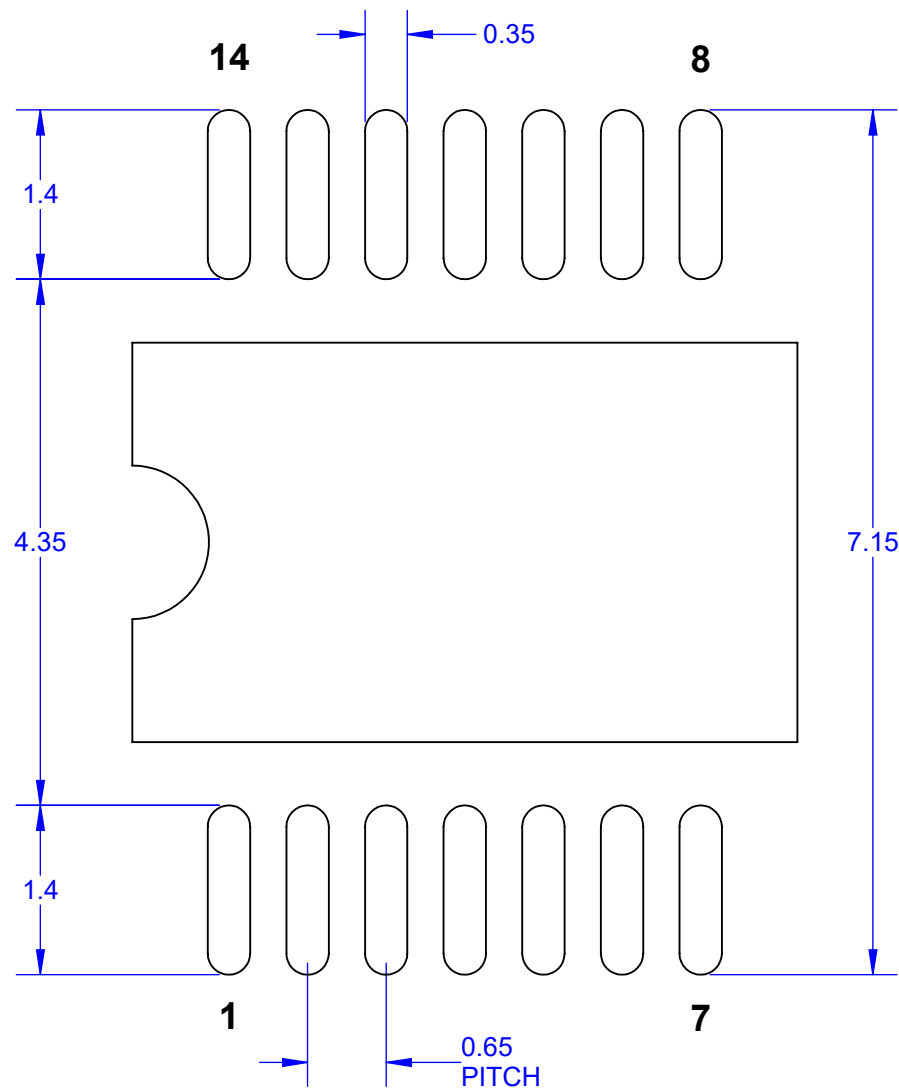
TAPE SPECIFICATION TSSOP14 SURFACE MOUNT DEVICE



ALL DIMENSIONS IN mm

TopLine®			
TITLE		TSSOP14 JUMPER OUTLINE PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131414	A
DO NOT SCALE DRAWING			SHEET 5 OF 7

PC BOARD LAND PATTERN



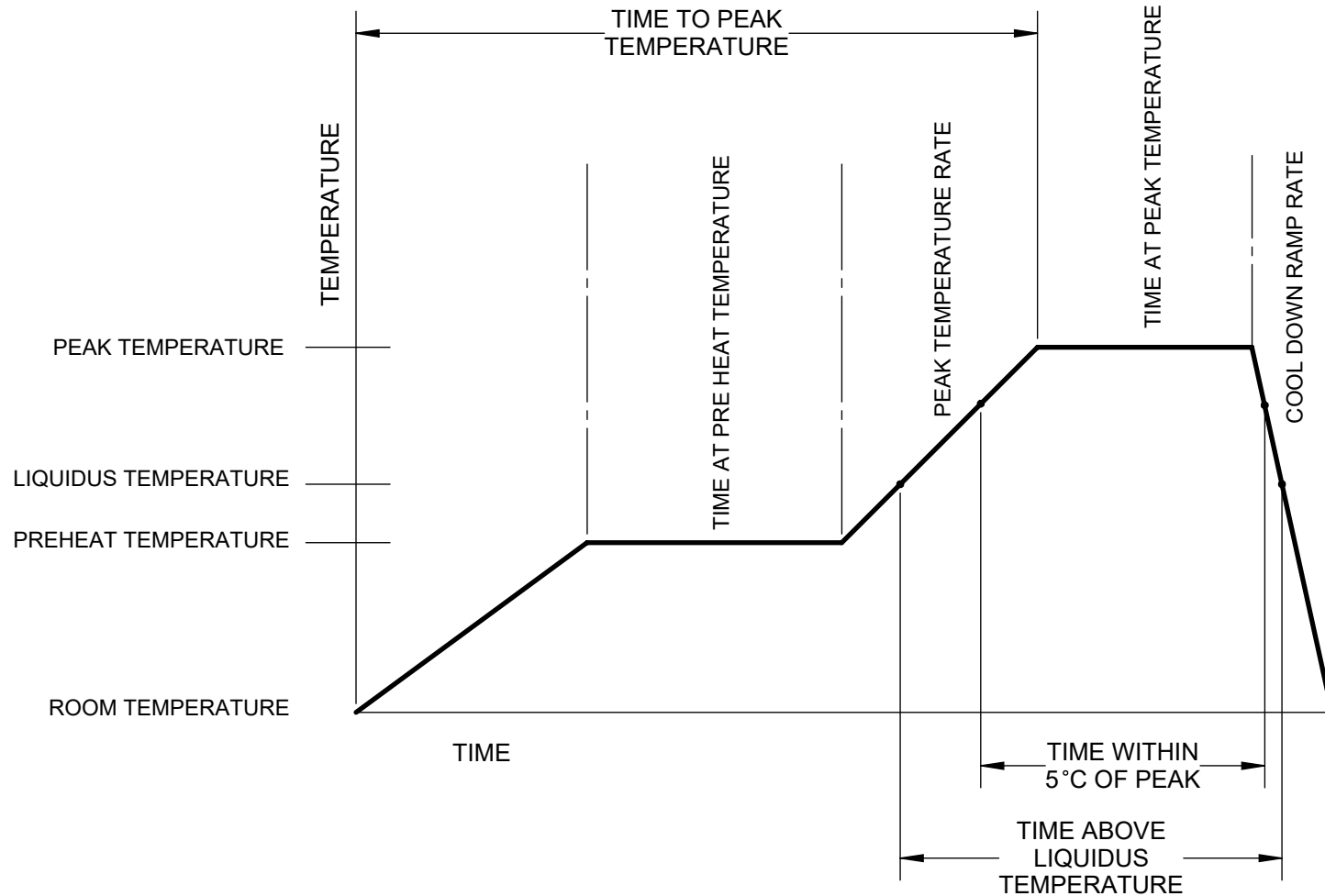
Notes: (Unless Otherwise Specified)

- 1) DIMENSIONS ARE IN mm.
- 2) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
- 3) DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

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TITLE			
TSSOP14 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
16:1	A	131414	A
DO NOT SCALE DRAWING			SHEET 6 OF 7

LEAD FREE REFLOW PROFILE OF SMD PACKAGE



DESCRIPTION	REQUIREMENT
AVERAGE PREHEAT RAMP RATE	3 °C/SECOND MAXIMUM
PREHEAT TEMPERATURE	150 °C MAXIMUM, 200 °C MAXIMUM
PREHEAT TIME	60 TO 80 SECONDS
RAMP TO PEAK	3 °C/SECOND MAXIMUM
TIME OVER LIQUIDUS (217°C)	60 TO 150 SECONDS
PEAK TEMPERATURE	260 °C +0/-5 °C
TIME WITHIN 5°C OF PEAK	20 TO 40 SECONDS
RAMP - COOL DOWN	6 °C/SECONDS MAXIMUM
TIME 25°C TO PEAK	8 MINUTES MAXIMUM

TopLine®

TITLE			
TSSOP14 JUMPER OUTLINE PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
NONE	A	131414	A
DO NOT SCALE DRAWING			SHEET 7 OF 7